

**Lead Frame Format Change of Select
QFP Products in Amkor Philippines**

**Qualification Results Summary for
QFP at AP1**


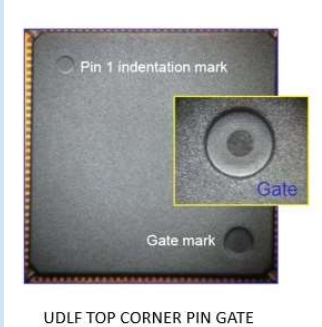
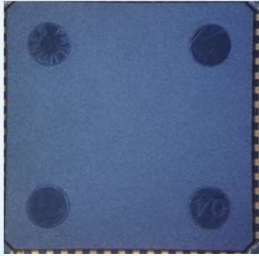
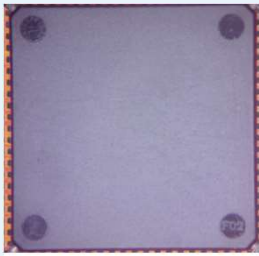
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	PASS
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	ANSI/ESDA/JEDEC <i>JS-002</i>	3/voltage	PASS ±1250V

* Preconditioned per JEDEC/IPC J-STD-020.

Materials Change Description

MATERIALS	FROM	TO	REMARKS
Die Attach	Ablestik 8361J	Ablestik 8361J	Same
Wire type	Gold Wire	Gold Wire	Same
Mold Compound	Sumitomo G700LS	Sumitomo G631HQ	G631HQ is qualified
Lead Finish	Matte Sn	Matte Sn	Same

Appearance Change

Package	FROM: OMLF	TO: UDLF	Remarks
Top Package Appearance	 <p>MATRIX BOTTOM CORNER GATE</p>	 <p>UDLF TOP CORNER PIN GATE</p>	<p>OMLF: Corner mold gate UDLF: Top mold gate</p> <p>Package Dimensions: No change</p>
Bottom Package Appearance	 <p>OMLF BOTTOM PACKAGE</p>	 <p>UDLF BOTTOM PACKAGE</p>	<p>Package Dimensions: No change</p>